




Features

- Metal foil chip design for overcurrent protection
- EIA 0603 (1608 metric) footprint
- Small chip size with high current rating and inrush withstanding capability
- Agency recognition:  us
- RoHS* compliant and halogen free**

Applications

- Data centers
- Industrial
- Medical (low to medium risk)***
- Telecom
- Battery Management Systems (BMS)

SF-0603SP-R Series – Metal Foil SMD Fuses

Clearing Time Characteristics for Series

% of Current Rating	Clearing Time at 25 °C	
	Min.	Max.
100 %	4 hours	—
200 %	1 second	120 seconds

Additional Information

Click these links for more information:



Electrical Characteristics

Model	Rated Current (A)	Resistance (Ω) Typ. ¹	Rated Voltage ¹	Interrupting Rating	Typical I ² t (A ² s) ²	Certification
						cUL: E198545
SF-0603SP100R-2	1.0	0.115	63 VDC	50 A @ 63 VDC	0.059	✓
SF-0603SP150R-2	1.5	0.059			0.13	✓
SF-0603SP200R-2	2.0	0.033			0.21	✓
SF-0603SP300R-2	3.0	0.0159			0.71	✓
SF-0603SP400R-2	4.0	0.01			0.96	✓
SF-0603SP500R-2	5.0	0.00677			2.05	✓
SF-0603SP600R-2	6.0	0.0063			3.47	✓
SF-0603SP700R-2	7.0	0.0047			5.04	✓
SF-0603SP800R-2	8.0	0.0043			6.5	✓

Notes:

1. Resistance value measured with ≤10 % rated current at 25 °C ambient. Tolerance ±25 %.
2. Melting I²t calculated at 0.001 second pre-arcing time.

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WARNING Cancer and Reproductive Harm
www.P65Warnings.ca.gov

*RoHS Directive 2015/863, Mar 31, 2015 and Annex.

**Bourns considers a product to be “halogen free” if (a) the Bromine (Br) content is 900 ppm or less; (b) the Chlorine (Cl) content is 900 ppm or less; and (c) the total Bromine (Br) and Chlorine (Cl) content is 1500 ppm or less.

***Bourns® products have not been designed and are not intended for use in “lifesaving,” “life-critical,” or “life-sustaining” applications nor any other applications where failure or malfunction of the Bourns® product may result in personal injury or death. See Legal Disclaimer Notice on the last page of this document or at <http://www.bourns.com/docs/legal/disclaimer.pdf>

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Specifications are subject to change without notice.

Users should verify actual device performance in their specific applications.

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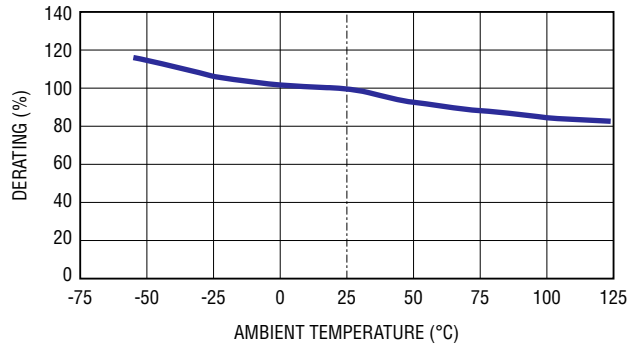
SF-0603SP-R Series – Metal Foil SMD Fuses



Environmental Characteristics

Operating Temperature	-55 °C to +125 °C
Storage Conditions	
Temperature	+5 °C to +35 °C
Humidity	40 % to 75 %
Moisture Sensitivity Level	1
ESD Classification	Class 6

Current Rating Thermal Derating Curve



Typical Part Marking

Represents total content. Layout may vary. Markings in white color.



Rated Current	Part Marking	Rated Current	Part Marking
1 A	L	5 A	Y
1.5 A	P	6 A	6
2 A	S	7 A	Z
3 A	3	8 A	8
4 A	W		

How to Order

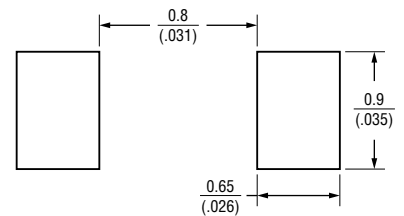
SF - 0603 SP 100 R - 2

SinglFuse™ _____
 Product Designator _____
 SMD Footprint _____
 0603 = EIA 0603 (1608 metric)
 Fusing Characteristic _____
 SP = 1~120 sec. @ 200 % I_N
 Rated Current _____
 100~800 = 1 A~8 A
 Structure Type _____
 R = Metal Foil
 Packaging Type _____
 - 2 = Tape & Reel

Packaging

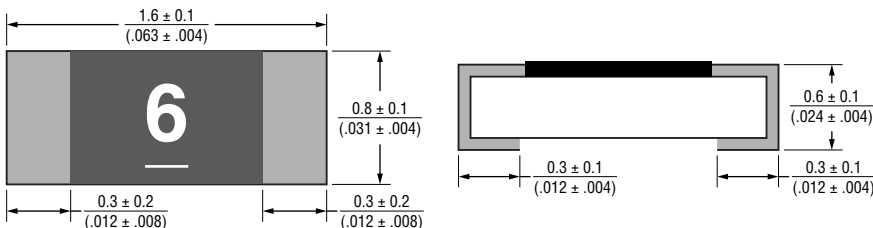
Reel Dimension	7-inch Tape and Reel
Specification	EIA 481-2
Quantity	5,000 pieces
Packaging Code	-2

Recommended Pad Layout



DIMENSIONS: $\frac{\text{MM}}{\text{(INCHES)}}$

Product Dimensions



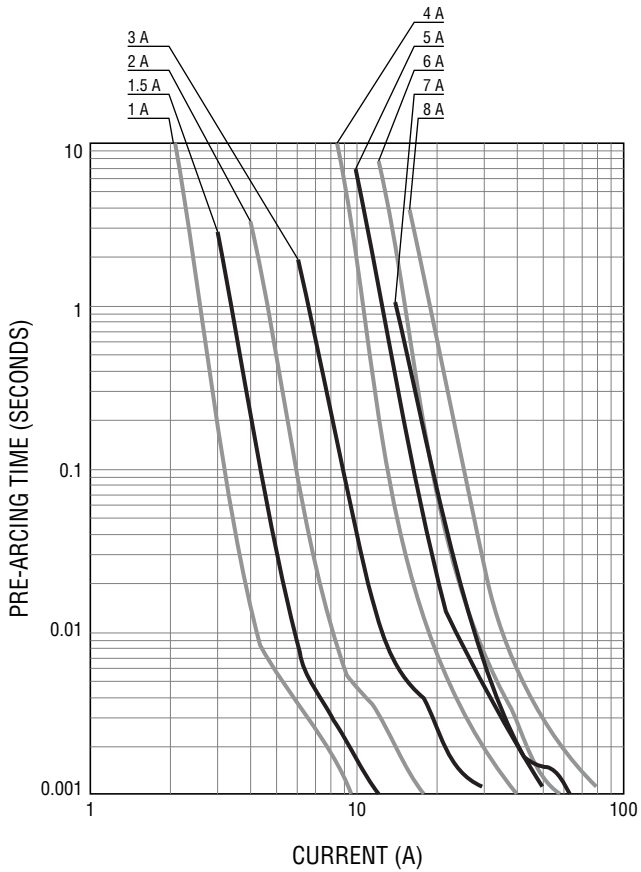
DIMENSIONS: $\frac{\text{MM}}{\text{(INCHES)}}$

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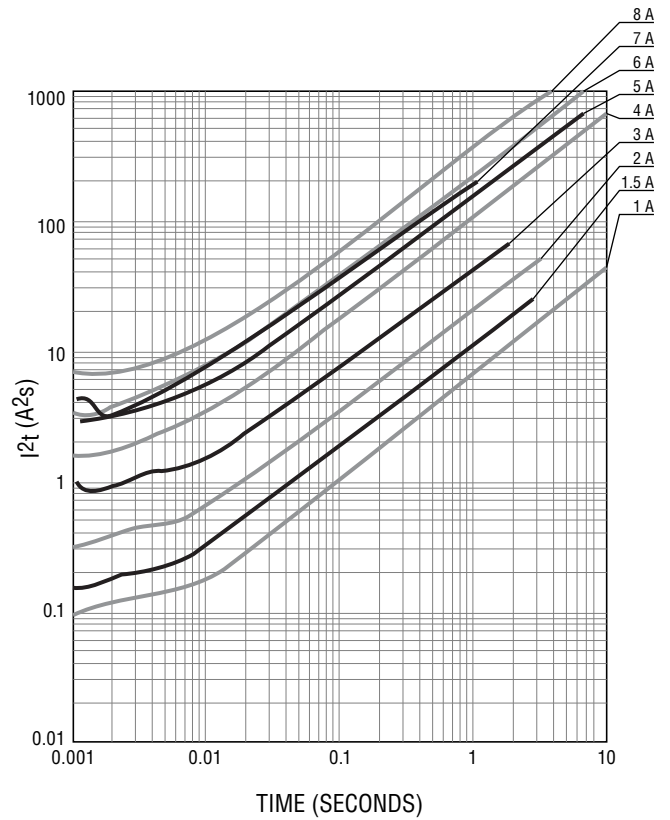
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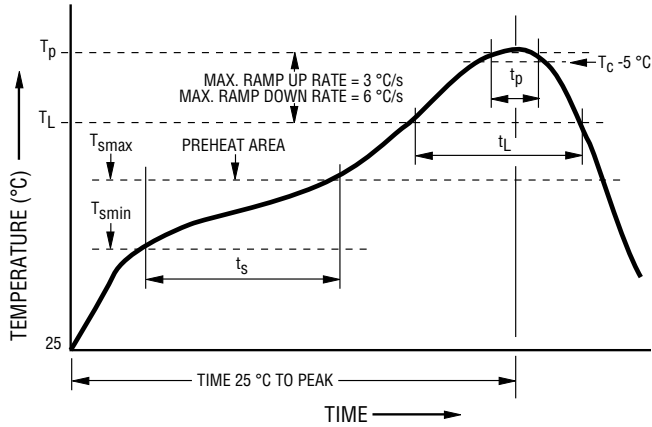
Average Pre-Arcing Time vs. Current Curves



Average I^2t vs. t Curves



Solder Reflow Recommendations



Profile Feature	Pb-Free Assembly
Preheat / Soak: Temperature Min. (T_{smin}) Temperature Max. (T_{smax}) Time (t_s) from (T_{smin} to T_{smax})	150 °C 200 °C 60~120 seconds
Ramp Up Rate (T_L to T_p)	3 °C / second max.
Liquidous Temperature (T_L) Time (t_L) maintained above T_L	217 °C 60~150 seconds
Peak Package Body Temperature (T_p)	260 °C
Time (t_p)* within 5 °C of the specified classification temperature (T_c)	30 seconds*
Ramp Down Rate (T_p to T_L)	6 °C / second max.
Time 25 °C to Peak Temperature	8 minutes max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

